

been revised to provide underlining for added text, as required on page 2 of the June 3, 2005 Office Action.

AMENDMENTS TO THE SPECIFICATION

Please amend paragraph [0042] to read as follows:

[0042] Also, a mother material of the above-described multilayer wiring board 3 is a ceramic-based, a glass-ceramic-based, or a glass-epoxy-based electric insulating material. Generally, a problem is often caused that, since electric insulating materials also have a low thermal conductivity, use of such materials in an original state results in an increase in thermal resistance of an entire device. Even if a back side of the device is kept at temperature below a certain value, a heating area in the semiconductor device can experience an extreme rise in temperature to cause thermorunaway of or breakage, in some cases, of the device. In Fig. 11, a reference numeral 22 denotes a collector wiring and 23 denotes a base wiring.